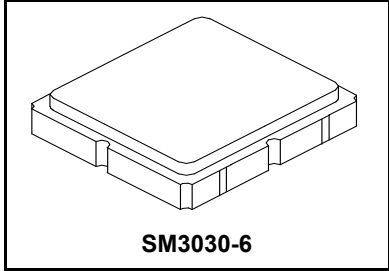


SF2241E

**2595 MHz
SAW Filter**



- *Low-loss RF SAW Filter*
- *Surface Mount 3.0 x 3.0 x 1.3 mm Package*
- *Complies with Directive 2002/95/EC (RoHS)*
- *Moisture Sensitivity Level: 1*

Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	10	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-30 to +85	°C
Storage Temperature Range	-40 to +95	°C
Solder Reflow Temperature, 10 seconds, 5 cycles maximum	260	°C

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	F_C			2595		MHz
Maximum Insertion Loss, 2570 to 2620 MHz	IL			2.8	3.8	dB
Amplitude Ripple, 2570 to 2620MHz				1.1	1.8	dB _{p,p}
VSWR, 2570 to 2620 MHz				1.6	2	
Attenuation Referenced to 0 dB:						
DC to 200 MHz			40	52		dB
200 to 2485 MHz			35	39		
2485 to 2510 MHz			20	31		
2680 to 2705 MHz			20	55		
2705 to 3000 MHz			35	55		
3000 to 4900 MHz			20	35		
4900 to 6000 MHz			10	14		
Source Impedance	Z_S			50		Ω
Load Impedance	Z_L			50		
Temperature Coefficient of Frequency				-36		ppm/°C

Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	975, <u>YWWS</u>					
Standard Reel Quantity	Reel Size 7 Inch					500 Pieces/Reel
	Reel Size 13 Inch					3000 Pieces/Reel

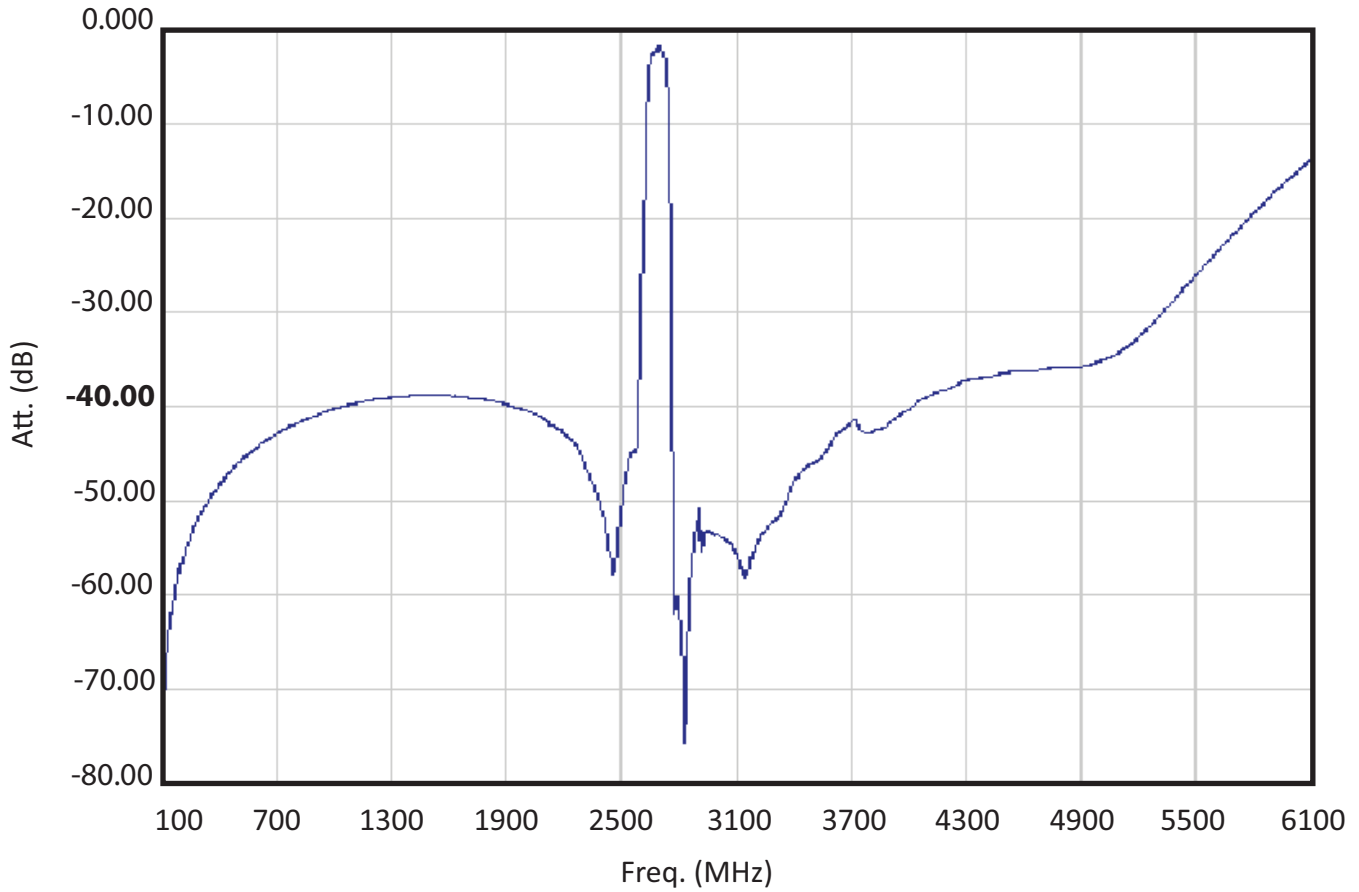


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

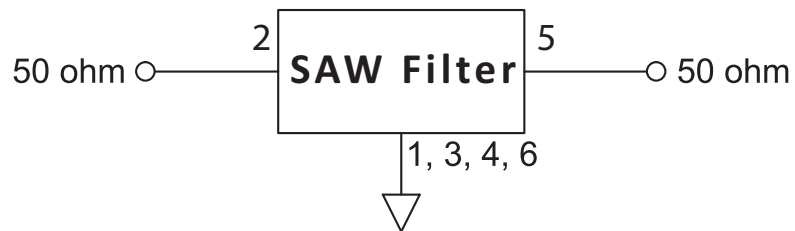
NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

Filter Broadband Response, 10 to 6000 MHz

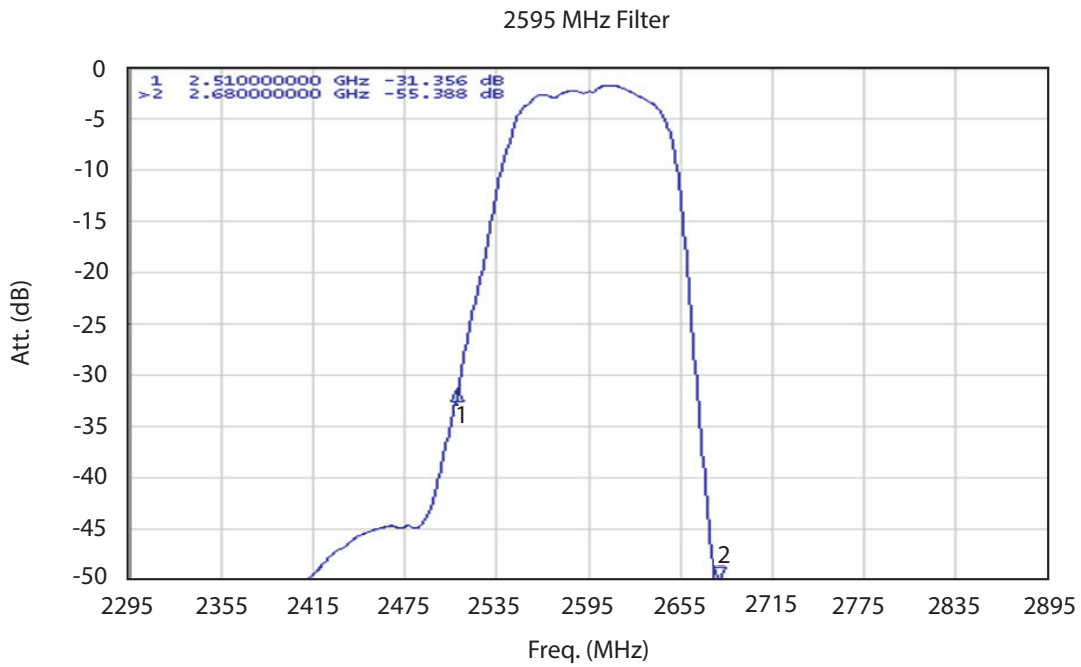


Filter Test Circuit

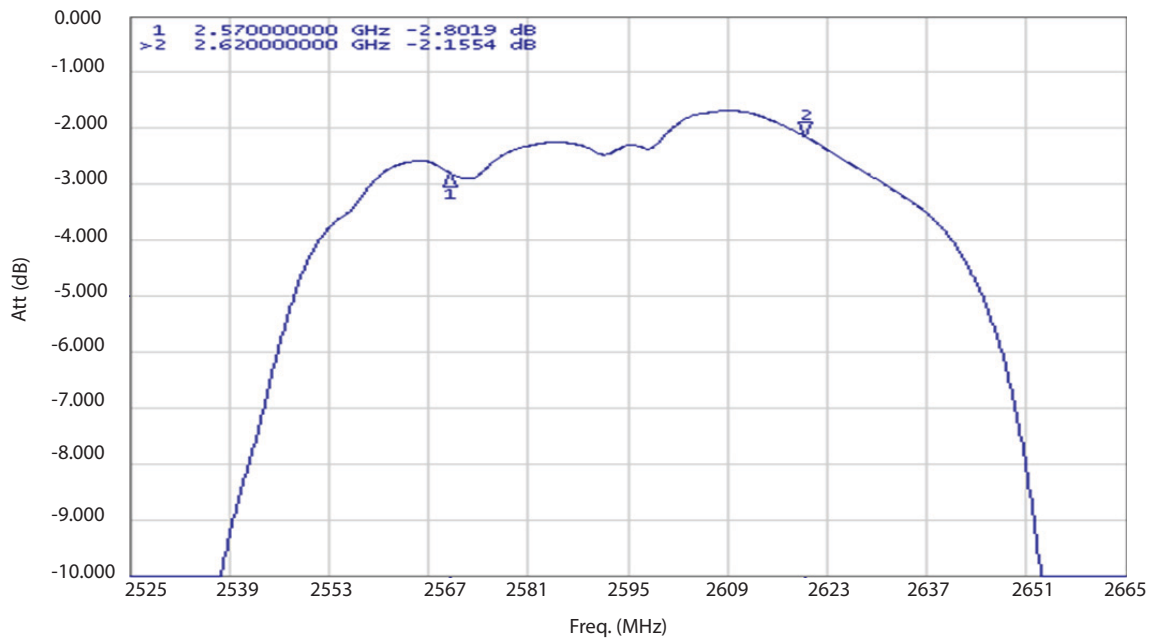


Connection	Terminals
Input	2
Output	5
Ground	All Others

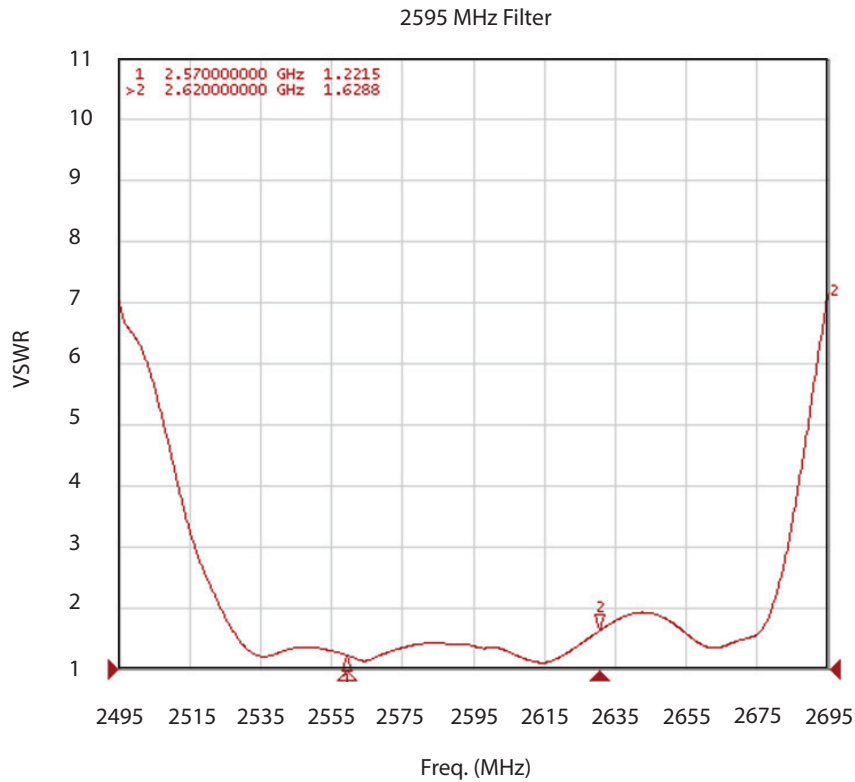
Filter Plot, 2295 to 2895 MHz



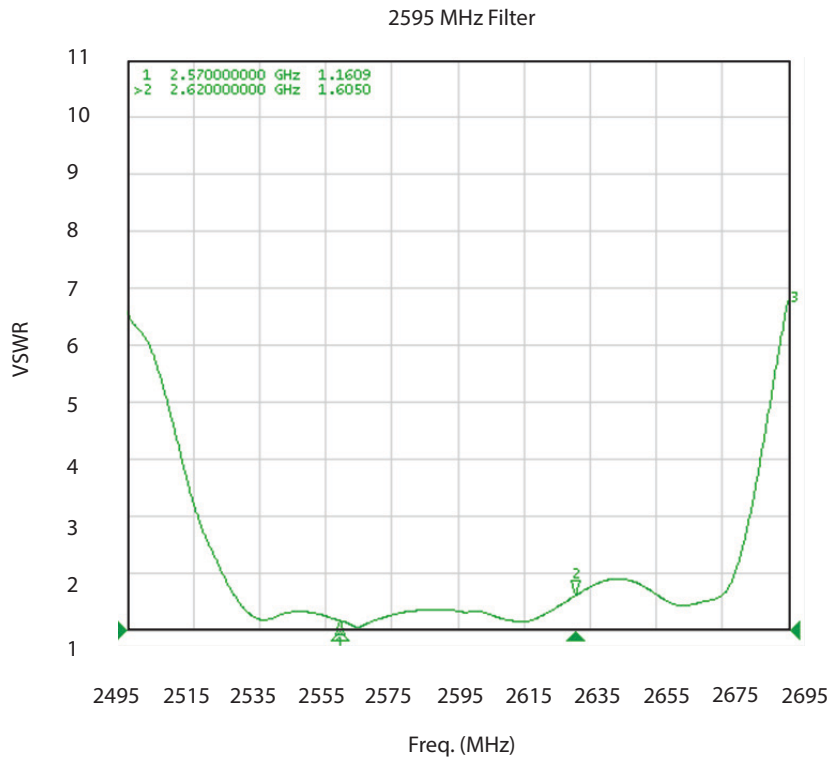
Filter Passband Plot, 2525 to 2665 MHz



Filter Input VSWR Plot, S11, 2495 to 2695 MHz

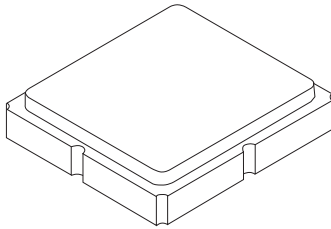


Filter Output VSWR Plot, S22, 2495 to 2695 MHz



SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

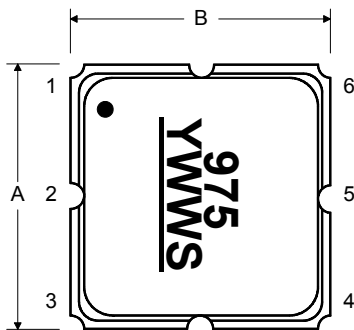
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.4	0.044	0.049	0.055
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

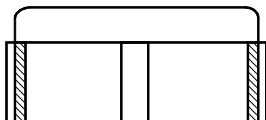
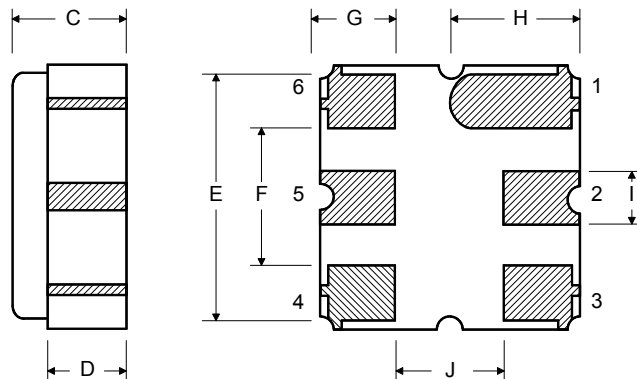
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μ m Gold over 1.27 to 8.89 μ m Nickel
Lid Plating	2.0 to 3.0 μ m Nickel
Body	Al ₂ O ₃ Ceramic

TOP VIEW

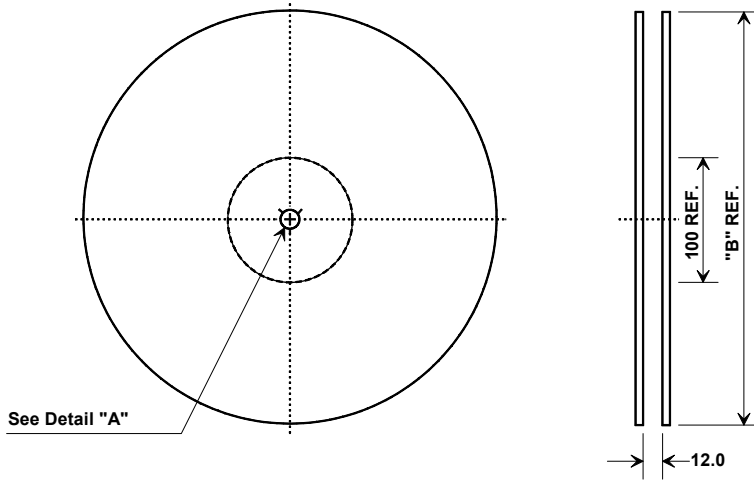


BOTTOM VIEW

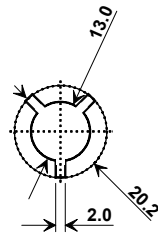


Tape and Reel Specifications

Tape and Reel Standard per ANSI/EIA481

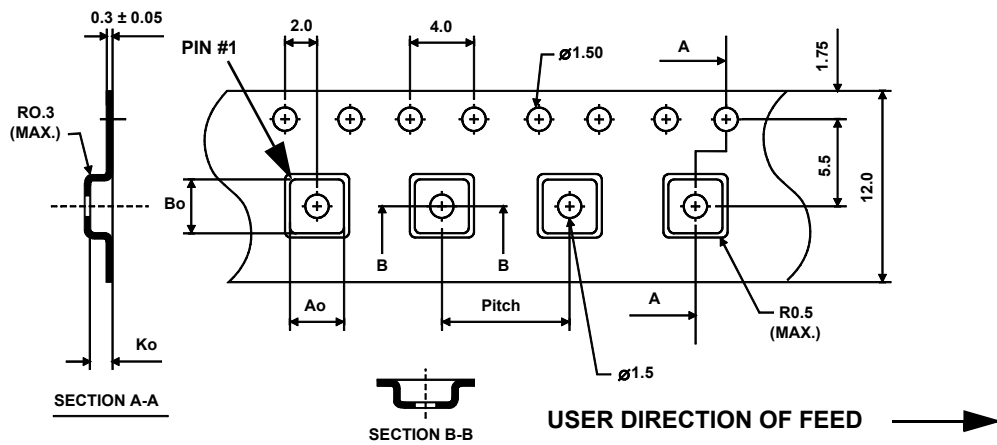


"B"		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000



COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	3.35 mm
Bo	3.35 mm
Ko	1.40 mm
Pitch	8.0 mm
W	12.0 mm



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180° for 60~90 seconds.
2. Ascending time to preheating temperature 150° shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C peak (10 seconds.)
4. Time: 5 times maximum

